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327,887

PATENT

2/7/97
PSS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : KIM

Examiner: T. BILODEAU

Serial No.: 08/327,887

Group Art Unit: 1107

RECEIVED

Filed : October 24, 1994

Docket: 9983.3-US-01 JAN 30 1997

Title : METHOD FOR FILLING CONTACT HOLES WITH METAL BY
TWO-STEP DEPOSITION

GROUP 110

January 2, 1997

AMENDMENT UNDER 37 C.F.R. §1.111

Hon. Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In response to the outstanding Office Action mailed November 8, 1996, please amend the above identified patent application as follows:

In the Claims

Please amend claims 1 and 9 as follows:

1. (Amended) A method for filling contact holes with metal by two-step deposition of metal layers, said method comprising the steps of:

providing a silicon substrate;

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